

LS110A-VIS-(C)

Acousto-Optic Deflector



0913

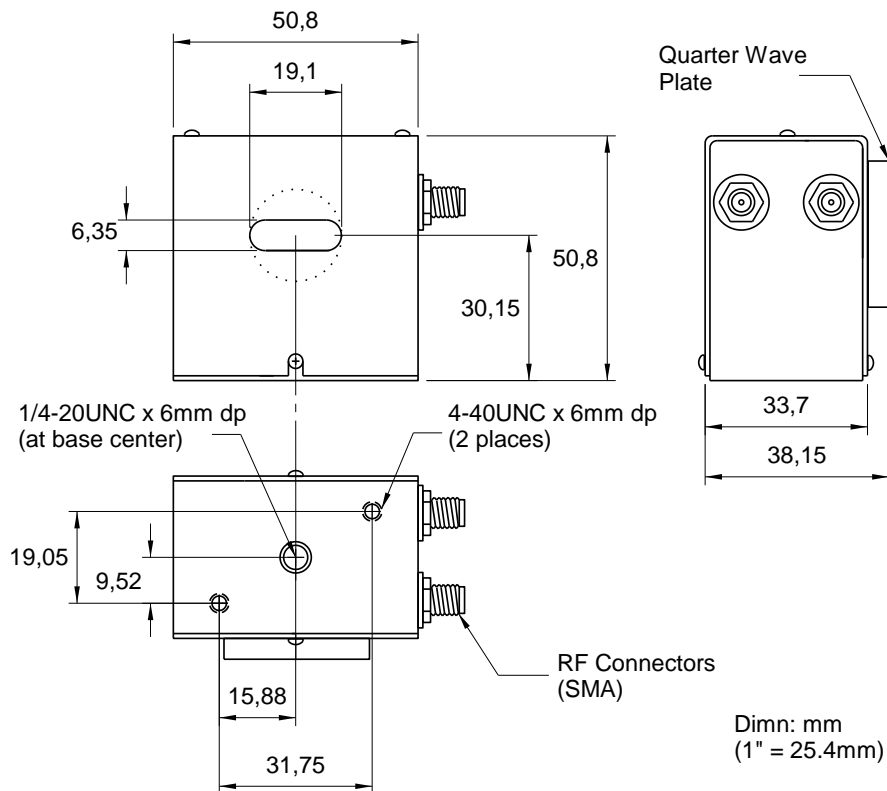
APPLICATIONS

- Solid State Scanning of Visible and Infrared Lasers

FEATURES

- High Resolution
- High Scan Speed
- No Moving Parts
- High Uniformity and Throughput across Scan

OUTLINE DRAWING



ALL SPECIFICATIONS SUBJECT TO CHANGE WITHOUT NOTICE

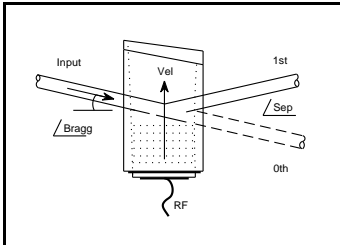
ISOMET CORP, 5263 Port Royal Rd, Springfield, VA 22151, USA.

Tel: (703) 321 8301 Fax: (703) 321 8546

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Quality Assured.

In-house: Crystal Growth,
Optical Polishing,
A/R coating, Vacuum Bonding



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SPECIFICATIONS

	<u>LS110-442</u>	<u>LS110-500</u>	<u>LS110A-532</u>	<u>LS110-633</u>
Wavelength **:	442nm	488(515)nm	532nm	633nm
Centre Freq. (Nom)	120MHz	100MHz	100MHz	100MHz
Bandwidth Δf:	50MHz	50MHz	50MHz	50MHz
Scan Angle/Axis:	2.1°	2.3° (2.4°)	2.5°	2.9°
Separation Angle :	4.9°	4.5° (4.8°)	4.9°	5.9°
Aperture	9.3mm / 14x4mm	9.3mm / 14x4mm	9.3mm / 14x4mm	9.3mm / 14x4mm
Resolution:				
9.3mm Beam (-C)	750	750	750	750
14x4mm Beam	1100*	1100*	1100*	1100*

Aperture:

LS110-xxx-C
LS110-xxx

9.3mm diameter
14mm(W) x 4mm(H)

Access Time (t):

15 μs (-C) or 22.7 μs

Input Laser Polarization:

Linear. (Quarter wave plate included)

Output Laser Polarization:

Circular (Nominal)

Interaction Material:

TeO₂ (Slow Shear)

Acoustic Velocity:

0.617mm/μs

RF Input Impedance:

50Ω Nominal

Throughput Efficiency:

>60% Across Scan (75% Typical)

RF DRIVE ELECTRONICS

VCO driver/amplifier:

D323-BS / D333-BS

Fast tuning Synthesizer:

iHSA-2

Amplifier only:

DA134-p-xxx (with Integral Phase shifting)

* Theoretical Rayleigh resolution with uniformly illuminated aperture (14mm).

** Please call for other operating wavelengths.

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